

Assembly Transfer of Selected 12x12 TQFP_EP PPF Leadframe Based Products to Amkor Philippines

Qualification Plan Summary of 12x12 TQFP_EP Using G631HQ / CRM1076YB at Amkor Philippines

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Highly Accelerated Stress Test (HAST)*	JEDEC JESD22-A110	3 x 45	October 2015
Temperature Cycle (TC)*	JEDEC JESD22-A104	3 x 45	October 2015
Autoclave (AC)*	JEDEC JESD22-A102	3 x 45	October 2015
High Temperature Storage Life (HTSL)	JEDEC JESD22-A103	3 x 45	October 2015
Solder Heat Resistance (SHR)*	JEDEC/IPC J-STD-020	3 x 11	October 2015
Electrostatic Discharge Field-Induced Charged Device Model	JEDEC JESD22-C101	3/voltage	October 2015

*Preconditioned per JEDEC/IPC J-STD-020

FG Model	PkgType	BodySize	Pkg Lead Count	WIRE DIA. (BEFORE)	WIRE DIA. (AFTER)	EPOXY (BEFORE)	EPOXY (AFTER)	MOLD (BEFORE)	MOLD (AFTER)	MOLD GATE POSITION (BEFORE)	MOLD GATE POSITION (AFTER)
AD80350USVZ-105EP	TQFP_EP	12X12X1.0	80	1	1	8361J	CRM1076YB	GE7470LQ	G631HQ	Pkg corner	Pkg corner
AD9650USVZ-105EP	TQFP_EP	12X12X1.0	80	1	1	8361J	CRM1076YB	GE7470LQ	G631HQ	Pkg corner	Pkg corner
AD9650USVZR7-105EP	TQFP_EP	12X12X1.0	80	1	1	8361J	CRM1076YB	GE7470LQ	G631HQ	Pkg corner	Pkg corner